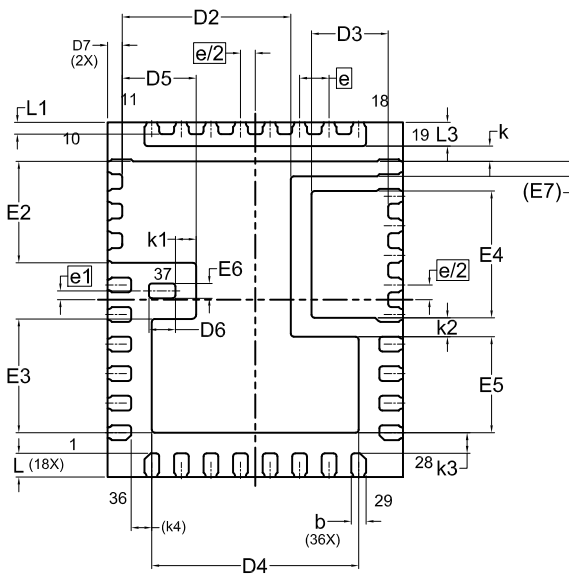
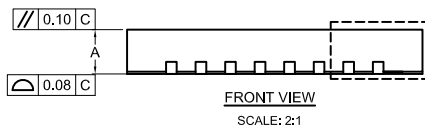
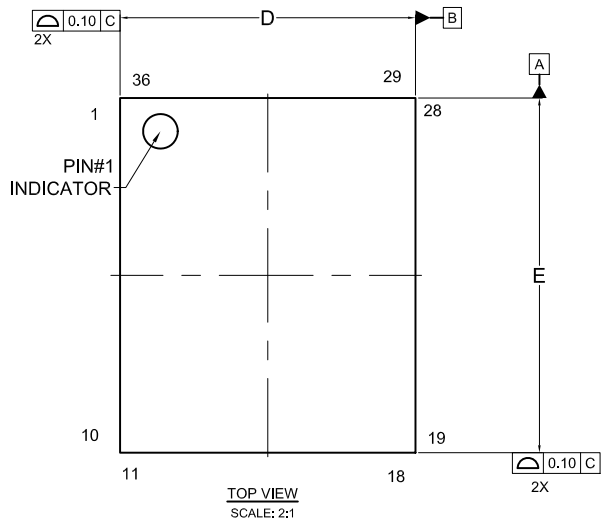
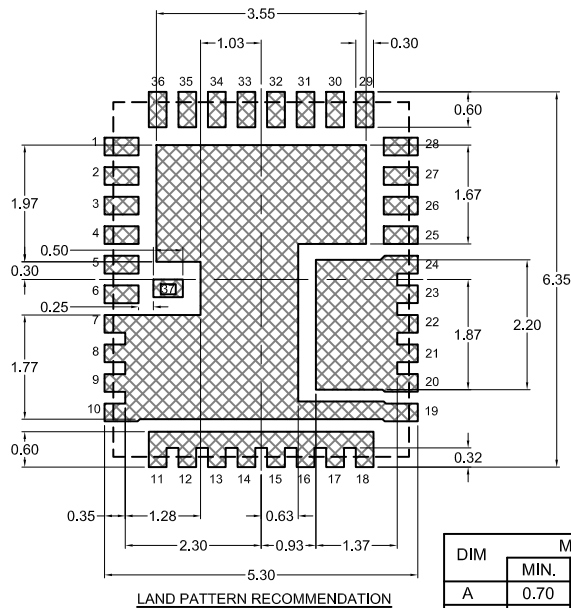


PQFN37 5x6, 0.5P
CASE 483BZ
ISSUE A

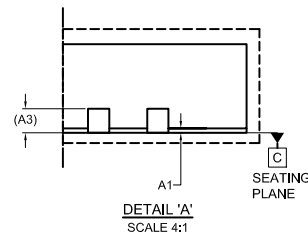
DATE 23 SEP 2022



BOTTOM VIEW
SCALE: 2:1



*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.



| DIM | MILLIMETERS | | |
|-----|-------------|------|------|
| | MIN. | NOM. | MAX. |
| A | 0.70 | 0.75 | 0.80 |
| A1 | 0.00 | - | 0.05 |
| A3 | 0.20 REF | | |
| b | 0.20 | 0.25 | 0.30 |
| D | 4.90 | 5.00 | 5.10 |
| D2 | 2.75 | 2.85 | 2.95 |
| D3 | 1.20 | 1.30 | 1.40 |
| D4 | 3.40 | 3.50 | 3.60 |
| D5 | 1.20 | 1.25 | 1.35 |
| D6 | 0.35 | 0.45 | 0.55 |
| D7 | 0.20 | 0.25 | 0.35 |
| E | 5.90 | 6.00 | 6.10 |
| E2 | 1.62 | 1.72 | 1.82 |
| E3 | 1.82 | 1.92 | 2.02 |
| E4 | 2.04 | 2.14 | 2.24 |
| E5 | 1.52 | 1.62 | 1.72 |
| E6 | 0.20 | 0.25 | 0.30 |
| E7 | 0.25 REF | | |
| e | 0.50 BSC | | |
| e/2 | 0.25 BSC | | |
| e1 | 0.15 BSC | | |
| k | 0.26 REF | | |
| k1 | 0.35 REF | | |
| k2 | 0.32 REF | | |
| k3 | 0.35 REF | | |
| k4 | 0.35 REF | | |
| L | 0.30 | 0.40 | 0.50 |
| L1 | 0.10 | 0.20 | 0.30 |
| L3 | 0.30 | 0.40 | 0.50 |

NOTES: UNLESS OTHERWISE SPECIFIED

- A) ALL DIMENSIONS ARE IN MILLIMETERS.
B) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.

GENERIC MARKING DIAGRAM*

XXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

XXXXXXXXXX
XXXXXXXXXX
AWLYYWW

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

| | | |
|-------------------------|-------------------------|---|
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| DESCRIPTION: | PQFN37 5X6, 0.5P | PAGE 1 OF 1 |

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